

SID

Factory: Rot am See

Article:

501

ML4

Provided:

Kracht, Enrico

Customer:

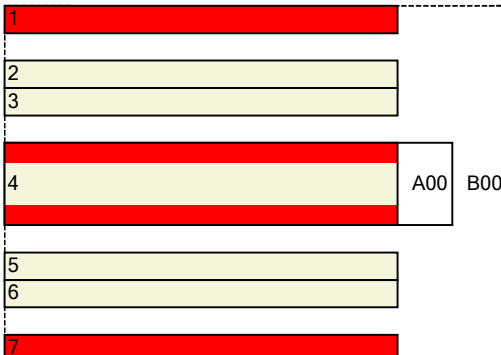
Date:

29.07.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	150		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
C-RS-FR4-DS-0.93mm-070+070-TG150-HF	50200935	70	L2	4	
		930			
		70	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	150		5	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	7	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1440 µm

Version 1.2.14.15

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